STACKED MICROELECTRONIC DEVICES AND METHODS FOR MANUFACTURING MICROELECTRONIC DEVICES

ABSTRACT OF THE DISCLOSURE

Stacked microelectronic devices and methods for manufacturing microelectronic devices are disclosed herein. An embodiment of one such microelectronic device can include a support member and a first known good microelectronic die attached to the support member. The first die includes an active side, a back side opposite the active side, a first terminal at the active side, and integrated circuitry electrically coupled to the first terminal. The first die also includes a first redistribution structure at the active side of the first die. The microelectronic device can also include a second known good microelectronic die attached to the first die in a stacked configuration such that a back side of the second die is facing the support member and an active side of the second die faces away from the support member. The second die includes a second redistribution structure at the active side of the second die. The device can further include a casing covering the first die, the second die, and at least a portion of the support member.

Figure : 3A